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September 5, 2002

Denise Sheridan for 20/E
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1/20/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Vishnu K. Agarwal
Serial No. : 09/652,993
Filed : August 31, 2000
Title : DEVICE AND METHOD FOR
CONDUCTIVE LAYER

Attorney Docket No.: 501082.04 (98-0616.03)
Group Art Unit : 2815
Examiner : Jose R. Diaz

Box Non-Fee Amendment
Commissioner of Patents
Washington, DC 20231

AMENDMENT

Sir:

Please amend the above-captioned patent application as follows:

In the Specification:

Please replace the paragraph beginning at page 8, line 4, with the following rewritten paragraph:

--Still other gases include diborane (B_2H_6); phosphine (PH_3); and carbon-silicon compounds such as methylsilane (CH_3SiH_3) and hexamethyldisilane ($CH_3)_3Si-Si(CH_3)_3$; and hexamethyldisilazane (HMDS). Additional alternate embodiments of the current invention use hydrazine (N_2H_4), monomethylhydrazine, carbon tetrafluoride (CF_4), CHF_3 , HCl , and boron trichloride (BCl_3), which are also useful in passivating dielectrics, as addressed in copending application 09/114,847, now issued as U.S. Patent No. 6,201,276 B1. Also included are mixtures of any of the gases or types of gases described above. Exemplary non-plasma process parameters using these other gases include a flow rate of about 2 sccm to about 400 sccm for

15